

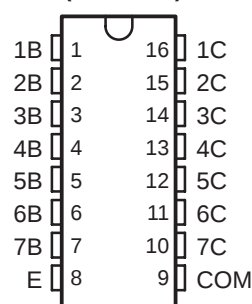
ULN2001A, ULN2002A, ULN2003A, ULN2004A, ULQ2003A, ULQ2004A HIGH-VOLTAGE HIGH-CURRENT DARLINGTON TRANSISTOR ARRAY

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

The ULN2001A is obsolete
and is no longer supplied.

- 500-mA-Rated Collector Current (Single Output)
- High-Voltage Outputs . . . 50 V
- Output Clamp Diodes
- Inputs Compatible With Various Types of Logic
- Relay-Driver Applications

ULN2001A . . . D OR N PACKAGE
ULN2002A . . . N PACKAGE
ULN2003A . . . D, N, NS, OR PW PACKAGE
ULN2004A . . . D, N, OR NS PACKAGE
ULQ2003A, ULQ2004A . . . D OR N PACKAGE
(TOP VIEW)



description/ordering information

The ULN2001A, ULN2002A, ULN2003A, ULN2004A, ULQ2003A, and ULQ2004A are high-voltage, high-current Darlington transistor arrays. Each consists of seven npn Darlington pairs that feature high-voltage outputs with common-cathode clamp diodes for switching inductive loads. The collector-current rating of a single Darlington pair is 500 mA. The Darlington pairs can be paralleled for higher current capability. Applications include relay drivers, hammer drivers, lamp drivers, display drivers (LED and gas discharge), line drivers, and logic buffers. For 100-V (otherwise interchangeable) versions of the ULN2003A and ULN2004A, see the SN75468 and SN75469, respectively.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–20°C to 70°C	PDIP (N)	Tube of 25	ULN2002AN	ULN2002AN
			ULN2003AN	ULN2003AN
			ULN2004AN	ULN2004AN
	SOIC (D)	Tube of 40	ULN2003AD	ULN2003A
		Reel of 2500	ULN2003ADR	
		Tube of 40	ULN2004AD	ULN2004A
		Reel of 2500	ULN2004ADR	
	SOP (NS)	Reel of 2000	ULN2003ANSR	ULN2003A
			ULN2004ANSR	ULN2004A
–40°C to 85°C	PDIP (N)	Tube of 25	ULN2003APW	UN2003A
			ULN2003APWR	
			ULQ2003AN	ULQ2003A
	SOIC (D)	Tube of 40	ULQ2004AN	ULQ2004AN
			ULQ2003AD	ULQ2003A
		Reel of 2500	ULQ2003ADR	ULQ2003A
		Tube of 40	ULQ2004AD	ULQ2004A
		Reel of 2500	ULQ2004ADR	ULQ2004A

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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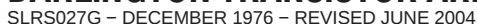
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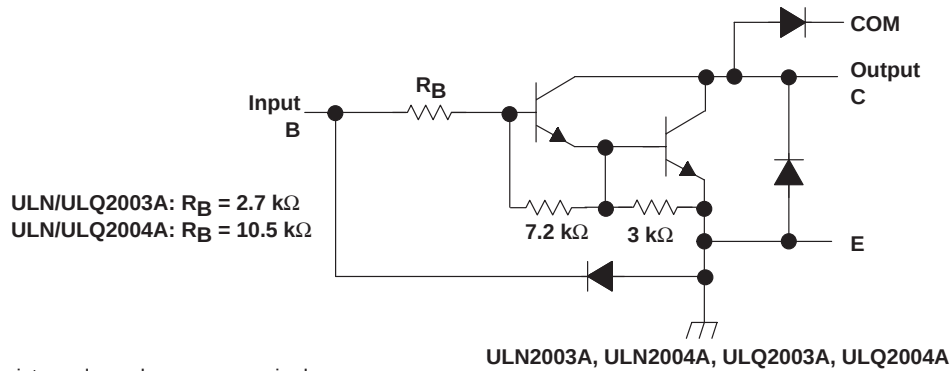
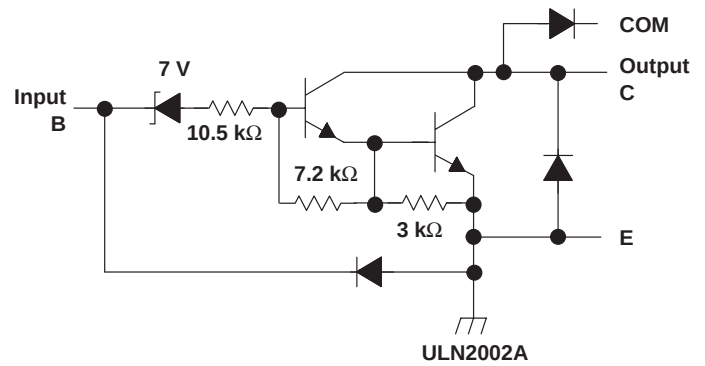
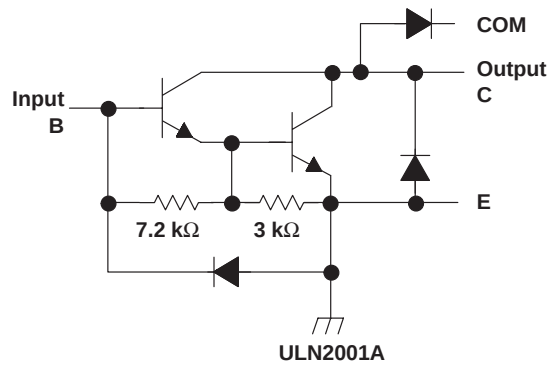


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HIGH-VOLTAGE HIGH-CURRENT DARLINGTON TRANSISTOR ARRAY

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

schematics (each Darlington pair)



All resistor values shown are nominal.

ULN2001A, ULN2002A, ULN2003A, ULN2004A, ULQ2003A, ULQ2004A

HIGH-VOLTAGE HIGH-CURRENT DARLINGTON TRANSISTOR ARRAY

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

The ULN2001A is obsolete
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absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)[†]

Collector-emitter voltage	50 V
Clamp diode reverse voltage (see Note 1)	50 V
Input voltage, V_I (see Note 1)	30 V
Peak collector current (see Figures 14 and 15)	500 mA
Output clamp current, I_{OK}	500 mA
Total emitter-terminal current	–2.5 A
Operating free-air temperature range, T_A , ULN200xA	–20°C to 70°C
ULQ200xA	–40°C to 85°C
ULQ200xAT	–40°C to 105°C
Package thermal impedance, θ_{JA} (see Notes 2 and 3): D package	73°C/W
N package	67°C/W
NS package	64°C/W
PW package	108°C/W
Package thermal impedance, θ_{JC} (see Notes 4 and 5): D package	36°C/W
N package	54°C/W
Operating virtual junction temperature, T_J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to the emitter/substrate terminal E, unless otherwise noted.
2. Maximum power dissipation is a function of $T_J(\max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JEDEC 51-7.
4. Maximum power dissipation is a function of $T_J(\max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(\max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
5. The package thermal impedance is calculated in accordance with MIL-STD-883.

electrical characteristics, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST FIGURE	TEST CONDITIONS	ULN2001A			ULN2002A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$V_{I(on)}$ On-state input voltage	6	$V_{CE} = 2\text{ V}$, $I_C = 300\text{ mA}$						13	V
$V_{CE(sat)}$ Collector-emitter saturation voltage	5	$I_I = 250\text{ }\mu\text{A}$, $I_C = 100\text{ mA}$		0.9	1.1		0.9	1.1	V
		$I_I = 350\text{ }\mu\text{A}$, $I_C = 200\text{ mA}$		1	1.3		1	1.3	
		$I_I = 500\text{ }\mu\text{A}$, $I_C = 350\text{ mA}$		1.2	1.6		1.2	1.6	
V_F Clamp forward voltage	8	$I_F = 350\text{ mA}$		1.7	2		1.7	2	V
I_{CEX} Collector cutoff current	1	$V_{CE} = 50\text{ V}$, $I_I = 0$			50			50	μA
	2	$V_{CE} = 50\text{ V}$, $T_A = 70^\circ\text{C}$, $I_I = 0$ $V_I = 6\text{ V}$			100			100	
								500	
$I_{I(off)}$ Off-state input current	3	$V_{CE} = 50\text{ V}$, $I_C = 500\text{ }\mu\text{A}$, $T_A = 70^\circ\text{C}$	50	65		50	65		μA
I_I Input current	4	$V_I = 17\text{ V}$					0.82	1.25	mA
I_R Clamp reverse current	7	$V_R = 50\text{ V}$, $T_A = 70^\circ\text{C}$			100			100	μA
		$V_R = 50\text{ V}$			50			50	
h_{FE} Static forward-current transfer ratio	5	$V_{CE} = 2\text{ V}$, $I_C = 350\text{ mA}$	1000						
C_i Input capacitance		$V_I = 0$, $f = 1\text{ MHz}$		15	25		15	25	pF



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**HIGH-VOLTAGE HIGH-CURRENT
DARLINGTON TRANSISTOR ARRAY**

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

electrical characteristics, $T_A = 25^\circ\text{C}$ (unless otherwise noted) (continued)

PARAMETER	TEST FIGURE	TEST CONDITIONS		ULN2003A			ULN2004A			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
$V_{I(on)}$ On-state input voltage	6	$V_{CE} = 2\text{ V}$	$I_C = 125\text{ mA}$						5	V
			$I_C = 200\text{ mA}$			2.4			6	
			$I_C = 250\text{ mA}$			2.7				
			$I_C = 275\text{ mA}$						7	
			$I_C = 300\text{ mA}$			3				
			$I_C = 350\text{ mA}$						8	
$V_{CE(sat)}$ Collector-emitter saturation voltage	5	$I_I = 250\text{ }\mu\text{A}$, $I_C = 100\text{ mA}$		0.9	1.1		0.9	1.1		V
		$I_I = 350\text{ }\mu\text{A}$, $I_C = 200\text{ mA}$		1	1.3		1	1.3		
		$I_I = 500\text{ }\mu\text{A}$, $I_C = 350\text{ mA}$		1.2	1.6		1.2	1.6		
I_{CEX} Collector cutoff current	1	$V_{CE} = 50\text{ V}$, $I_I = 0$			50			50		μA
	2	$V_{CE} = 50\text{ V}$, $T_A = 70^\circ\text{C}$, $I_I = 0$			100			100		
		$V_I = 1\text{ V}$						500		
V_F Clamp forward voltage	8	$I_F = 350\text{ mA}$		1.7	2		1.7	2		V
$I_{I(off)}$ Off-state input current	3	$V_{CE} = 50\text{ V}$, $T_A = 70^\circ\text{C}$, $I_C = 500\text{ }\mu\text{A}$		50	65		50	65		μA
I_I Input current	4	$V_I = 3.85\text{ V}$		0.93	1.35					mA
		$V_I = 5\text{ V}$					0.35	0.5		
		$V_I = 12\text{ V}$					1	1.45		
I_R Clamp reverse current	7	$V_R = 50\text{ V}$			50			50		μA
		$V_R = 50\text{ V}$, $T_A = 70^\circ\text{C}$			100			100		
C_i Input capacitance		$V_I = 0$, $f = 1\text{ MHz}$		15	25		15	25		pF

ULN2001A, ULN2002A, ULN2003A, ULN2004A, ULQ2003A, ULQ2004A

HIGH-VOLTAGE HIGH-CURRENT DARLINGTON TRANSISTOR ARRAY

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

The ULN2001A is obsolete
and is no longer supplied.

electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST FIGURE	TEST CONDITIONS		ULQ2003A			ULQ2004A			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
$V_{I(on)}$ On-state input voltage	6	$V_{CE} = 2\text{ V}$	$I_C = 125\text{ mA}$						5	V
			$I_C = 200\text{ mA}$			2.7			6	
			$I_C = 250\text{ mA}$			2.9				
			$I_C = 275\text{ mA}$						7	
			$I_C = 300\text{ mA}$			3				
			$I_C = 350\text{ mA}$						8	
$V_{CE(sat)}$ Collector-emitter saturation voltage	5	$I_I = 250\text{ }\mu\text{A}$, $I_C = 100\text{ mA}$		0.9	1.2		0.9	1.1		V
		$I_I = 350\text{ }\mu\text{A}$, $I_C = 200\text{ mA}$		1	1.4		1	1.3		
		$I_I = 500\text{ }\mu\text{A}$, $I_C = 350\text{ mA}$		1.2	1.7		1.2	1.6		
I_{CEX} Collector cutoff current	1	$V_{CE} = 50\text{ V}$, $I_I = 0$			100			50		μA
	2	$V_{CE} = 50\text{ V}$	$I_I = 0$					100		
			$V_I = 1\text{ V}$					500		
V_F Clamp forward voltage	8	$I_F = 350\text{ mA}$		1.7	2.3		1.7	2		V
$I_{I(off)}$ Off-state input current	3	$V_{CE} = 50\text{ V}$, $I_C = 500\text{ }\mu\text{A}$		65			50	65		μA
I_I Input current	4	$V_I = 3.85\text{ V}$		0.93	1.35					mA
		$V_I = 5\text{ V}$					0.35	0.5		
		$V_I = 12\text{ V}$					1	1.45		
I_R Clamp reverse current	7	$V_R = 50\text{ V}$, $T_A = 25^\circ\text{C}$			100			50		μA
		$V_R = 50\text{ V}$			100			100		
C_i Input capacitance		$V_I = 0$, $f = 1\text{ MHz}$		15	25		15	25		pF

switching characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	ULN2001A, ULN2002A, ULN2003A, ULN2004A			UNIT
		MIN	TYP	MAX	
t_{PLH} Propagation delay time, low- to high-level output	See Figure 9		0.25	1	μs
t_{PHL} Propagation delay time, high- to low-level output	See Figure 9		0.25	1	μs
V_{OH} High-level output voltage after switching	$V_S = 50\text{ V}$, $I_O \approx 300\text{ mA}$, See Figure 10	$V_S - 20$			mV

switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	ULQ2003A, ULQ2004A			UNIT
		MIN	TYP	MAX	
t_{PLH} Propagation delay time, low- to high-level output	See Figure 9		1	10	μs
t_{PHL} Propagation delay time, high- to low-level output	See Figure 9		1	10	μs
V_{OH} High-level output voltage after switching	$V_S = 50\text{ V}$, $I_O \approx 300\text{ mA}$, See Figure 10	$V_S - 500$			mV



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and is no longer supplied.

**HIGH-VOLTAGE HIGH-CURRENT
DARLINGTON TRANSISTOR ARRAY**

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

PARAMETER MEASUREMENT INFORMATION

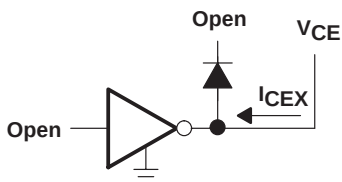


Figure 1. I_{CEX} Test Circuit

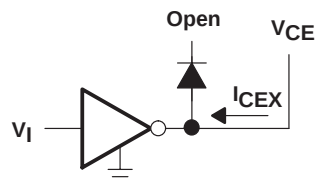


Figure 2. I_{CEX} Test Circuit

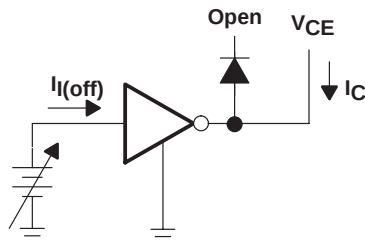


Figure 3. $I_{I(off)}$ Test Circuit

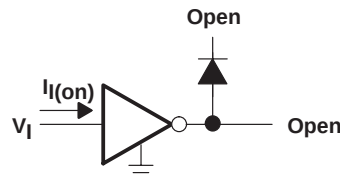
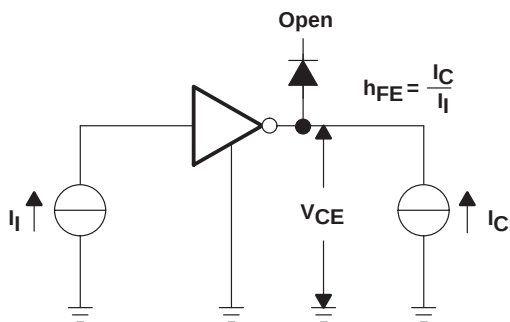


Figure 4. I_I Test Circuit



NOTE: I_I is fixed for measuring $V_{CE(sat)}$, variable for measuring h_{FE} .

Figure 5. h_{FE} , $V_{CE(sat)}$ Test Circuit

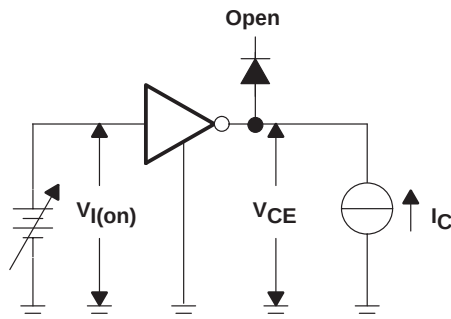


Figure 6. $V_{I(on)}$ Test Circuit

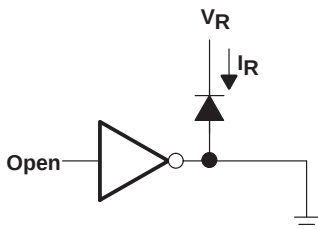


Figure 7. I_R Test Circuit

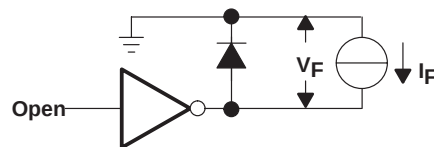


Figure 8. V_F Test Circuit

ULN2001A, ULN2002A, ULN2003A, ULN2004A, ULQ2003A, ULQ2004A HIGH-VOLTAGE HIGH-CURRENT DARLINGTON TRANSISTOR ARRAY

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

The ULN2001A is obsolete
and is no longer supplied.

PARAMETER MEASUREMENT INFORMATION

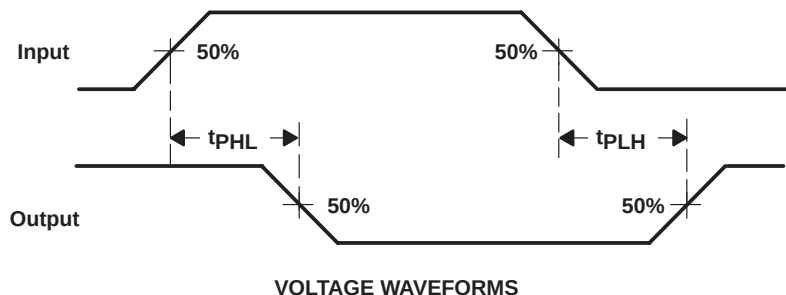
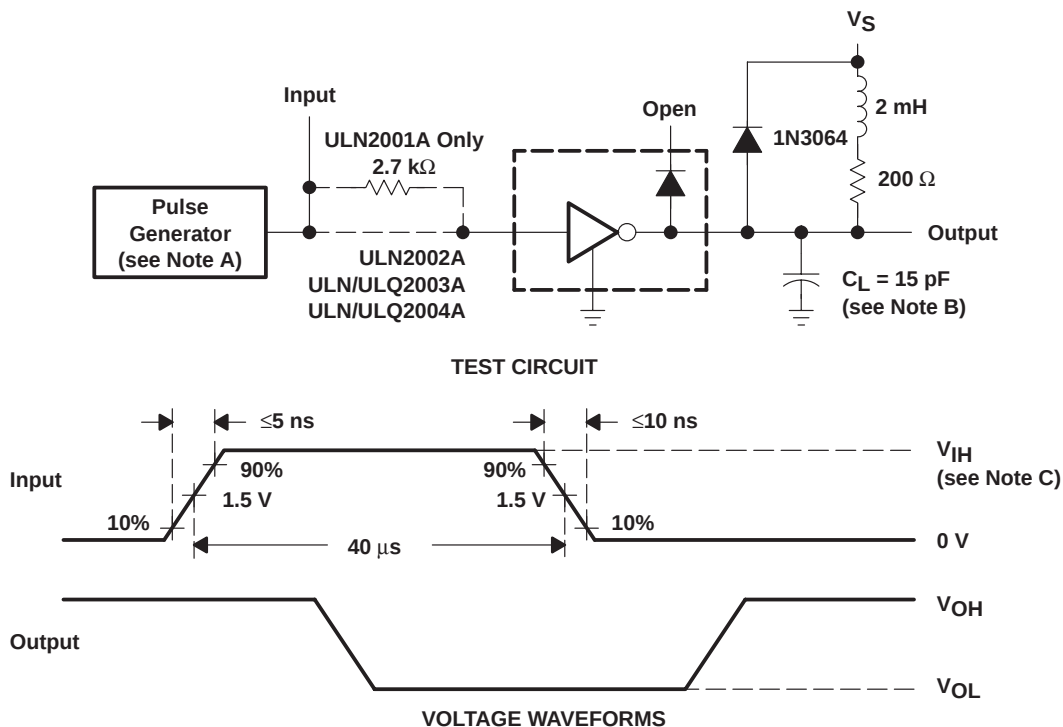


Figure 9. Propagation Delay-Time Waveforms



- NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz, $Z_O = 50 \Omega$.
B. C_L includes probe and jig capacitance.
C. For testing the ULN2001A, the ULN2003A, and the ULQ2003A, $V_{IH} = 3 \text{ V}$; for the ULN2002A, $V_{IH} = 13 \text{ V}$; for the ULN2004A and the ULQ2004A, $V_{IH} = 8 \text{ V}$.

Figure 10. Latch-Up Test Circuit and Voltage Waveforms

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HIGH-VOLTAGE HIGH-CURRENT DARLINGTON TRANSISTOR ARRAY

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

TYPICAL CHARACTERISTICS

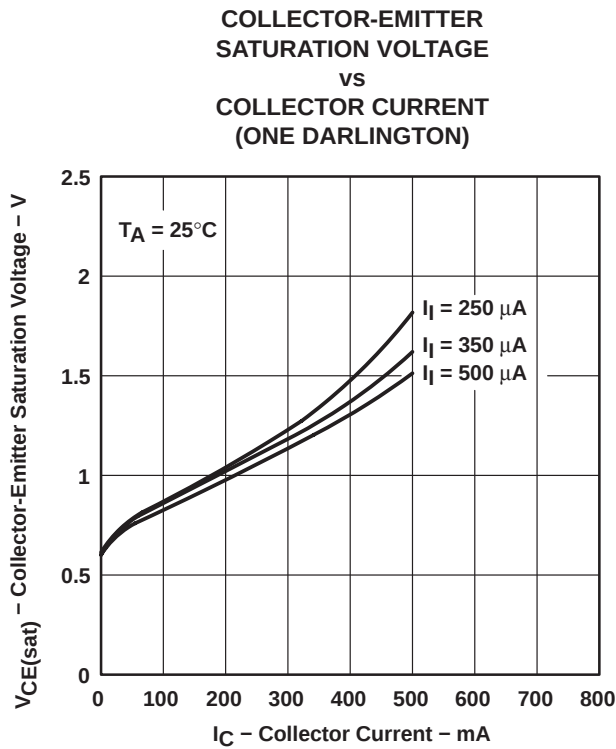


Figure 11

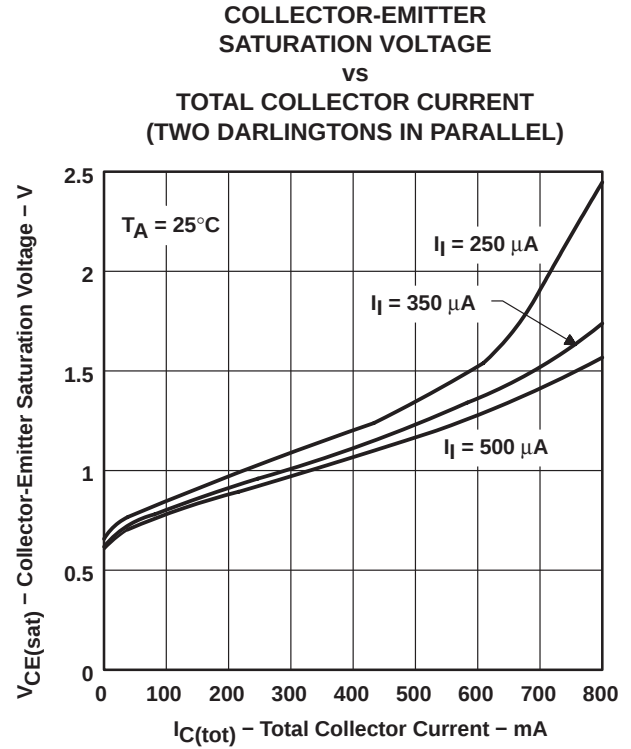


Figure 12

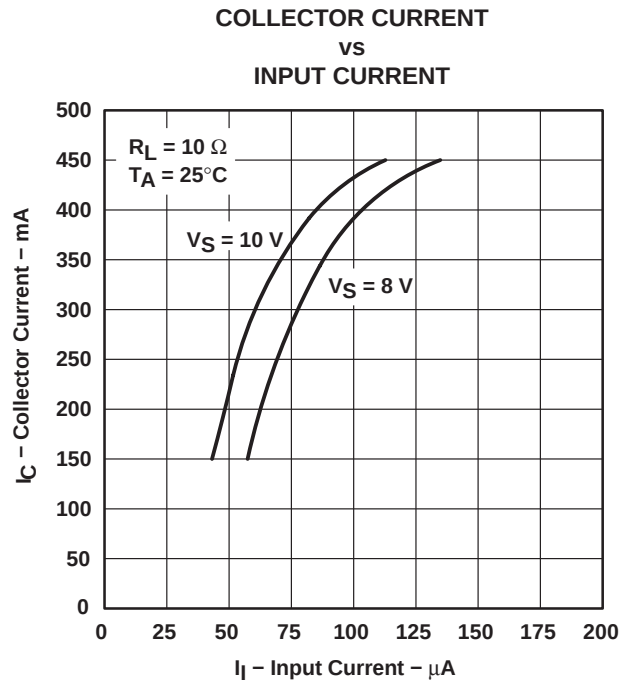


Figure 13

ULN2001A, ULN2002A, ULN2003A, ULN2004A, ULQ2003A, ULQ2004A

HIGH-VOLTAGE HIGH-CURRENT

DARLINGTON TRANSISTOR ARRAY

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

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THERMAL INFORMATION

D PACKAGE
MAXIMUM COLLECTOR CURRENT
VS
DUTY CYCLE

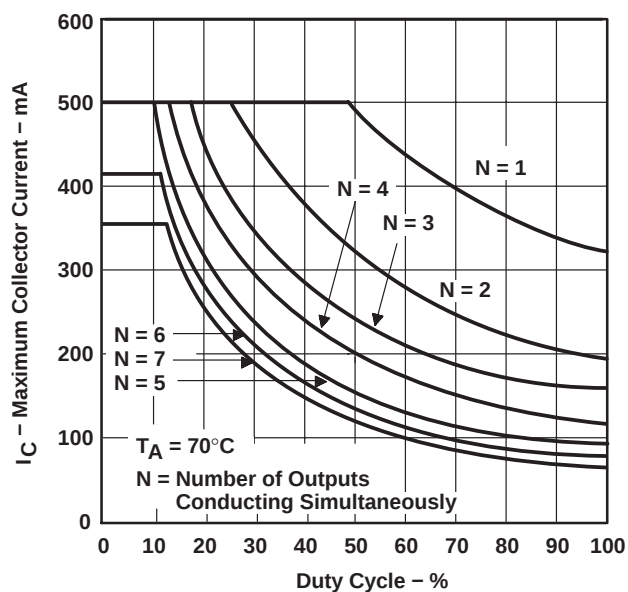


Figure 14

N PACKAGE
MAXIMUM COLLECTOR CURRENT
VS
DUTY CYCLE

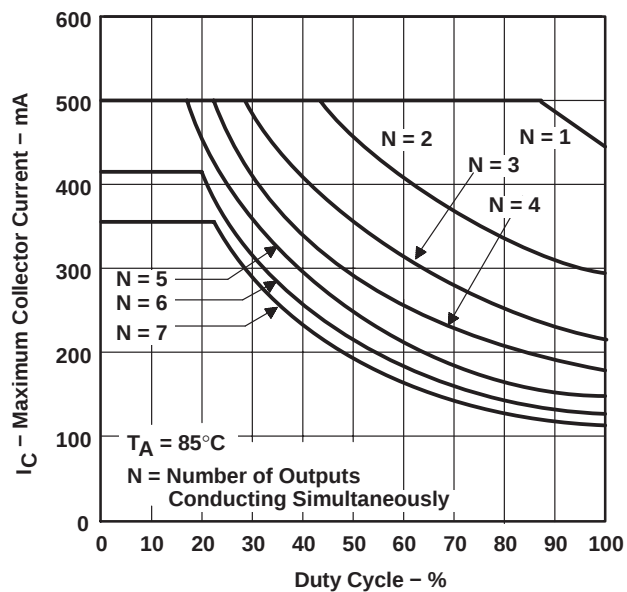


Figure 15

The ULN2001A is obsolete
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HIGH-VOLTAGE HIGH-CURRENT DARLINGTON TRANSISTOR ARRAY

SLRS027G – DECEMBER 1976 – REVISED JUNE 2004

APPLICATION INFORMATION

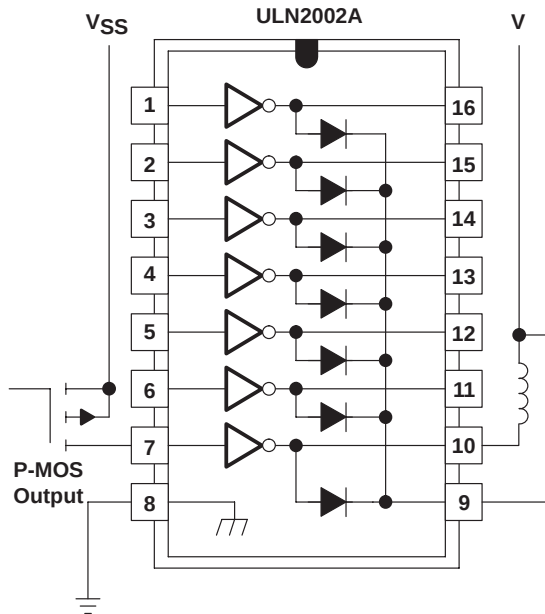


Figure 16. P-MOS to Load

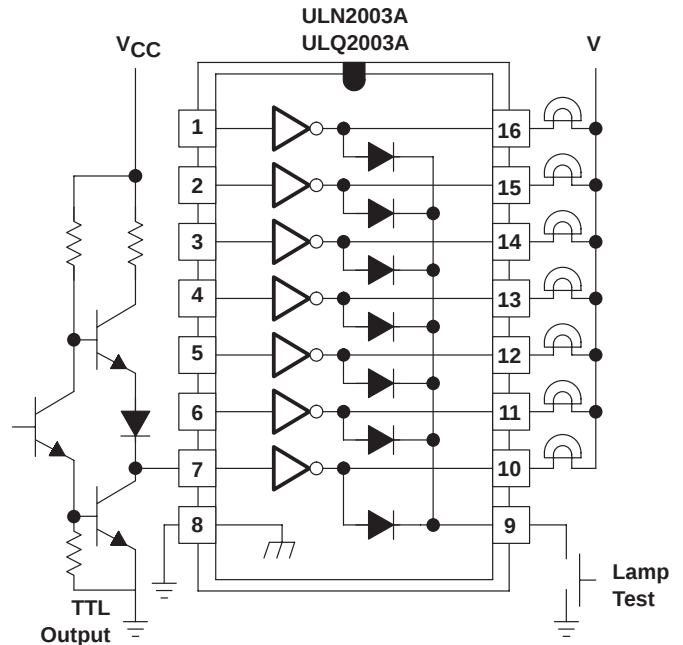


Figure 17. TTL to Load

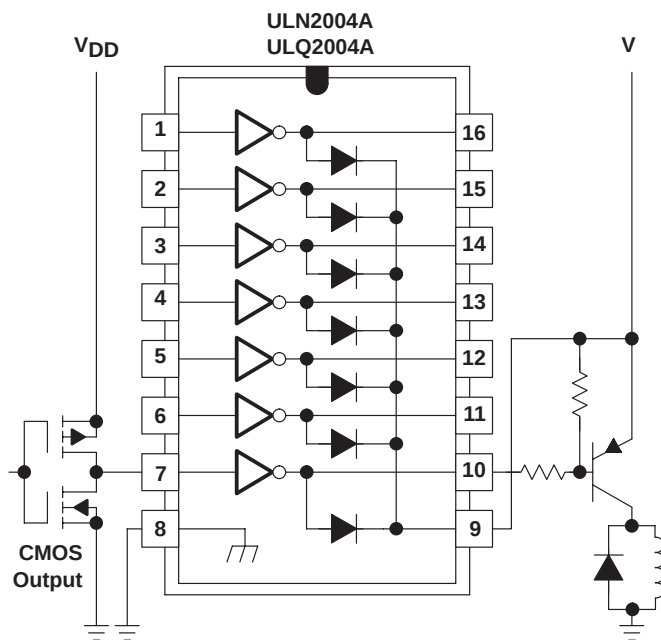


Figure 18. Buffer for Higher Current Loads

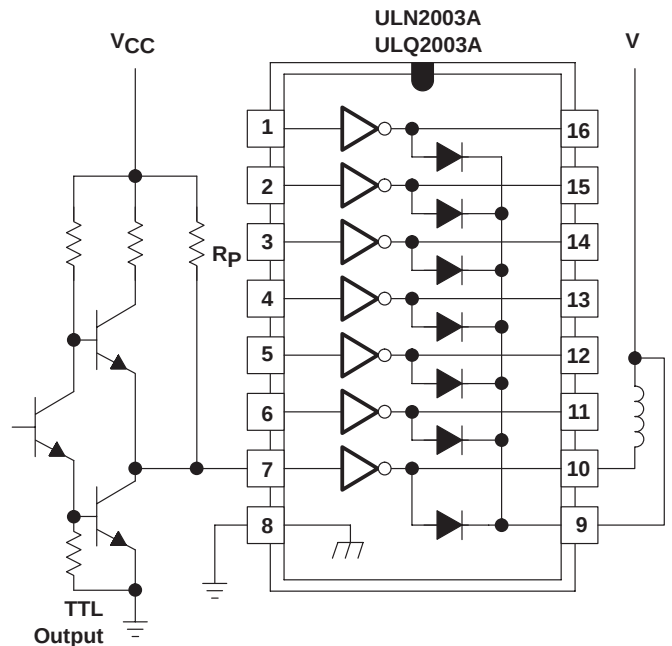


Figure 19. Use of Pullup Resistors
to Increase Drive Current

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
ULN2001AD	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
ULN2001ADR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
ULN2001AN	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
ULN2002AD	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
ULN2002AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
ULN2002ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
ULN2003AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003AJ	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
ULN2003AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
ULN2003ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
ULN2003ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003APWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003APWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2003APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2004AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2004ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2004ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
ULN2004ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2004ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2004ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2004AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
ULN2004ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
ULN2004ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULN2004ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULQ2003AD	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
ULQ2003ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULQ2003ADR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
ULQ2003ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULQ2003AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
ULQ2004AD	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
ULQ2004ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULQ2004ADR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
ULQ2004ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
ULQ2004AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF ULQ2003A, ULQ2004A :

- Automotive: [ULQ2003A-Q1](#), [ULQ2004A-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

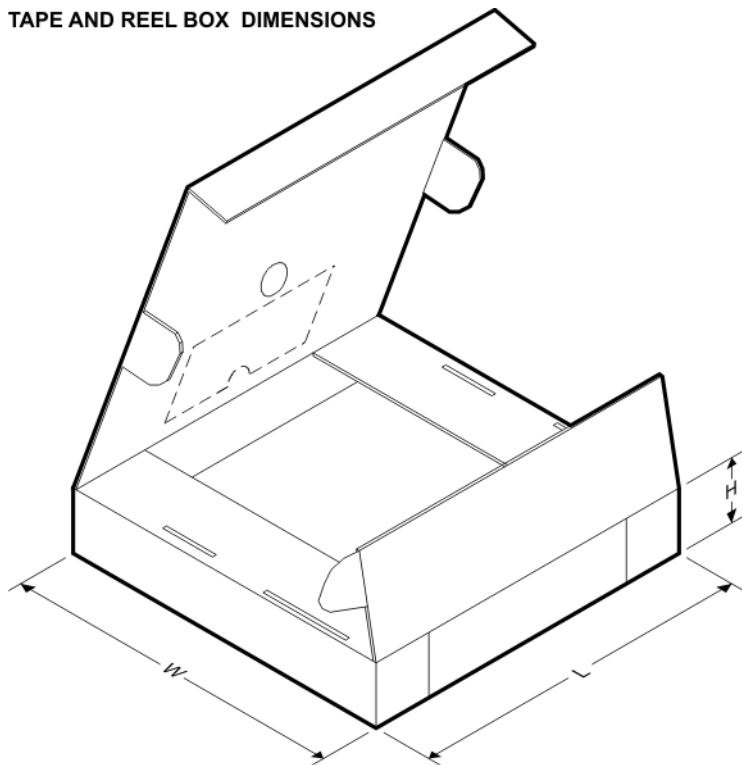
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ULN2003ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
ULN2003ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
ULN2003ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
ULN2003APWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
ULN2004ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
ULN2004ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
ULN2004ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ULN2003ADR	SOIC	D	16	2500	333.2	345.9	28.6
ULN2003ADR	SOIC	D	16	2500	346.0	346.0	33.0
ULN2003ANSR	SO	NS	16	2000	346.0	346.0	33.0
ULN2003APWR	TSSOP	PW	16	2000	346.0	346.0	29.0
ULN2004ADR	SOIC	D	16	2500	333.2	345.9	28.6
ULN2004ADR	SOIC	D	16	2500	346.0	346.0	33.0
ULN2004ANSR	SO	NS	16	2000	346.0	346.0	33.0

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

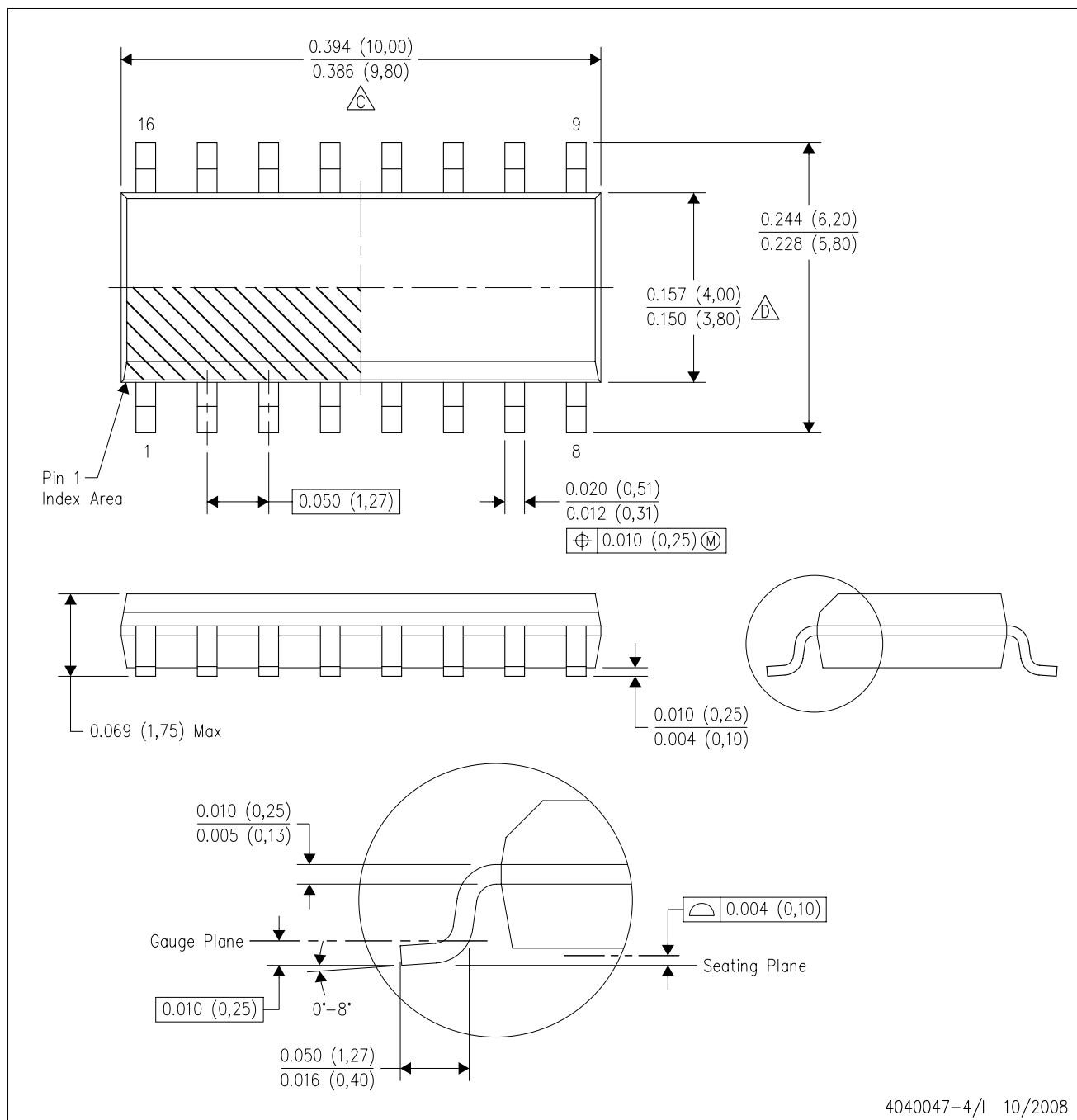
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

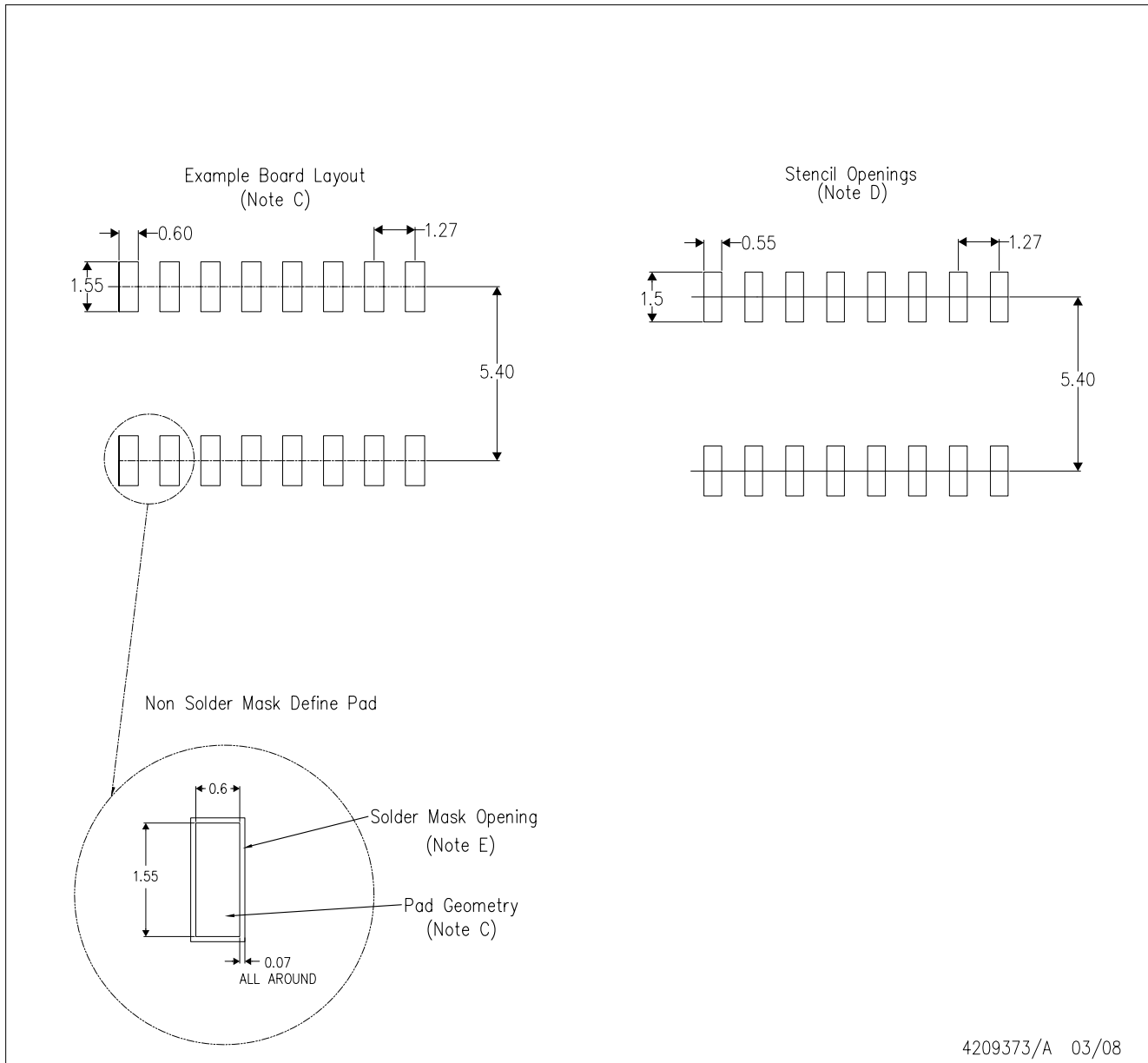
D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

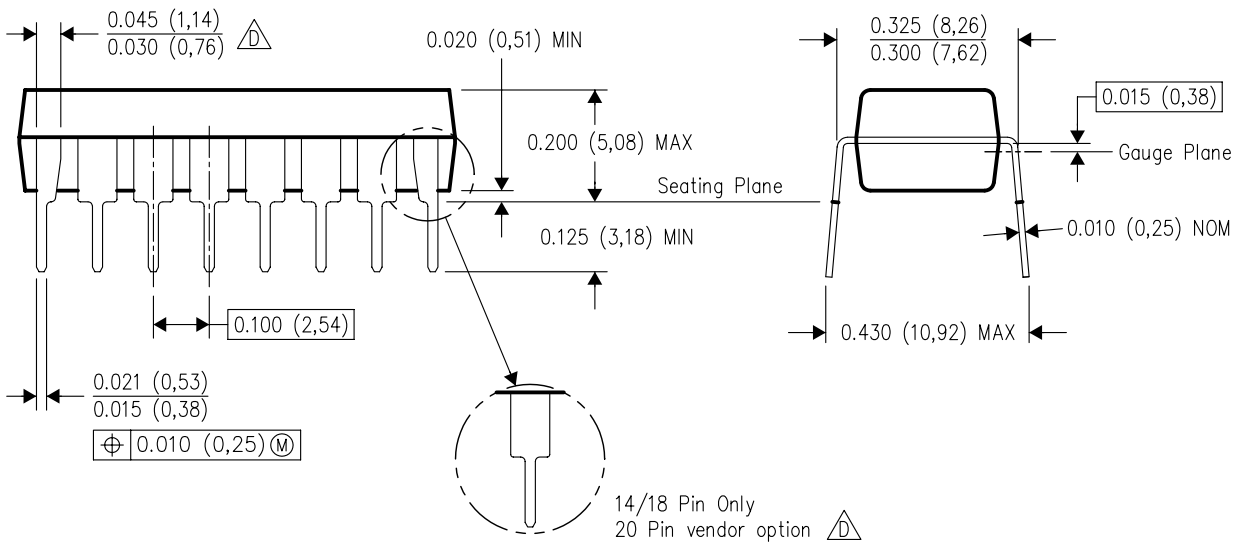
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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